

ECE1388 VLSI Design Methodology

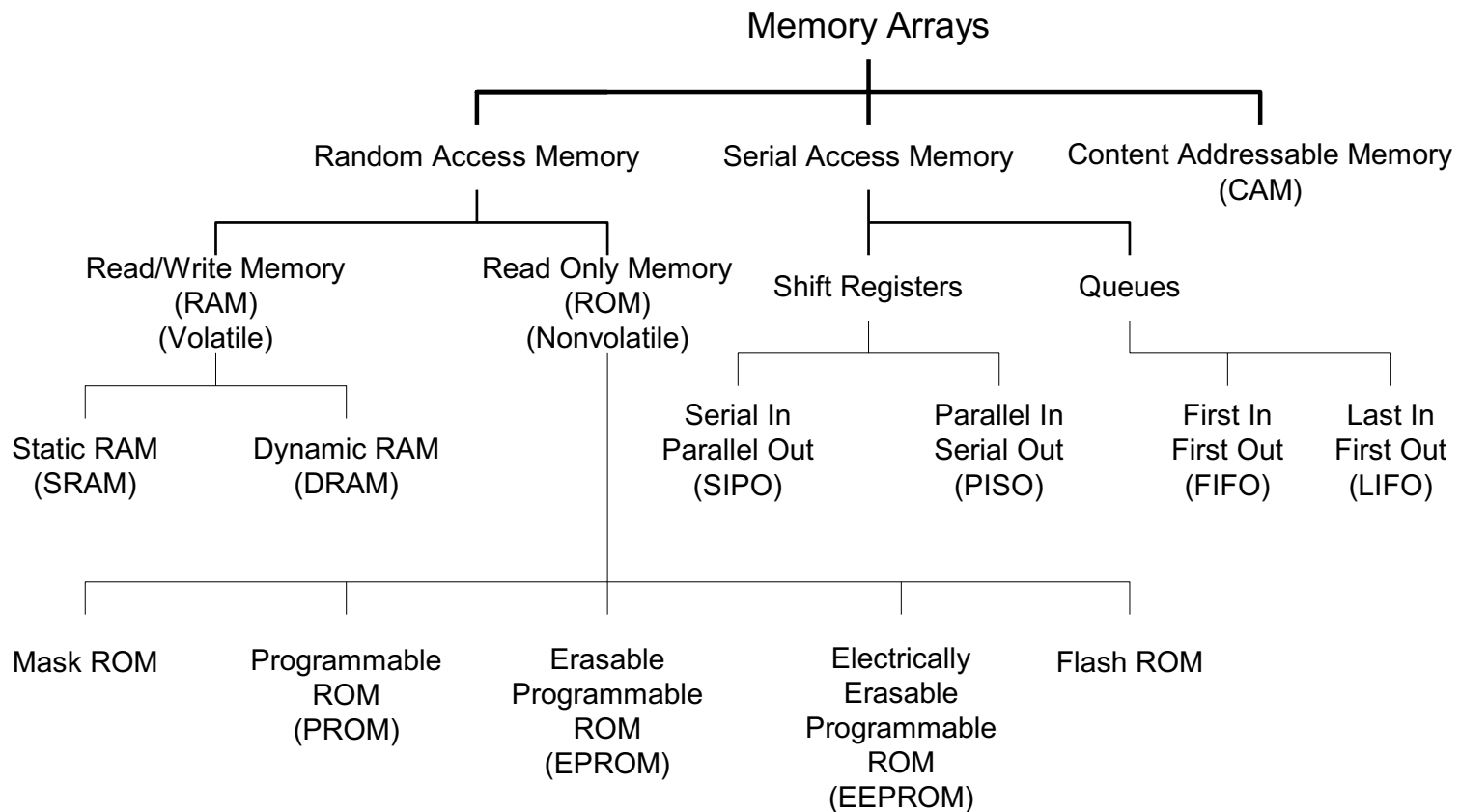
Lecture 13

Memories I: SRAM

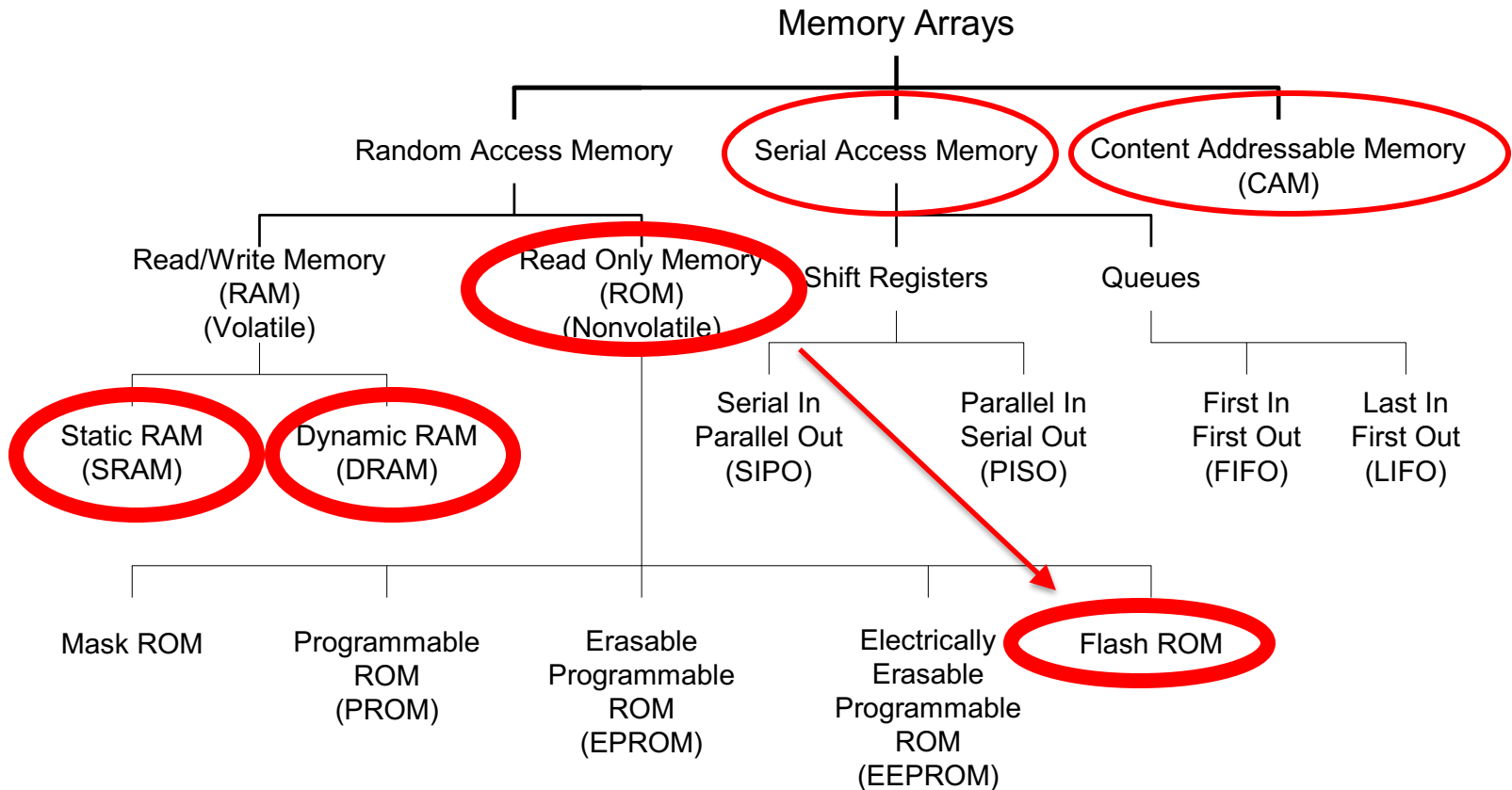
Outline

- ❑ Memory Arrays
- ❑ SRAM Architecture
 - SRAM Cell
 - Decoders
 - Column Circuitry
 - Multiple Ports

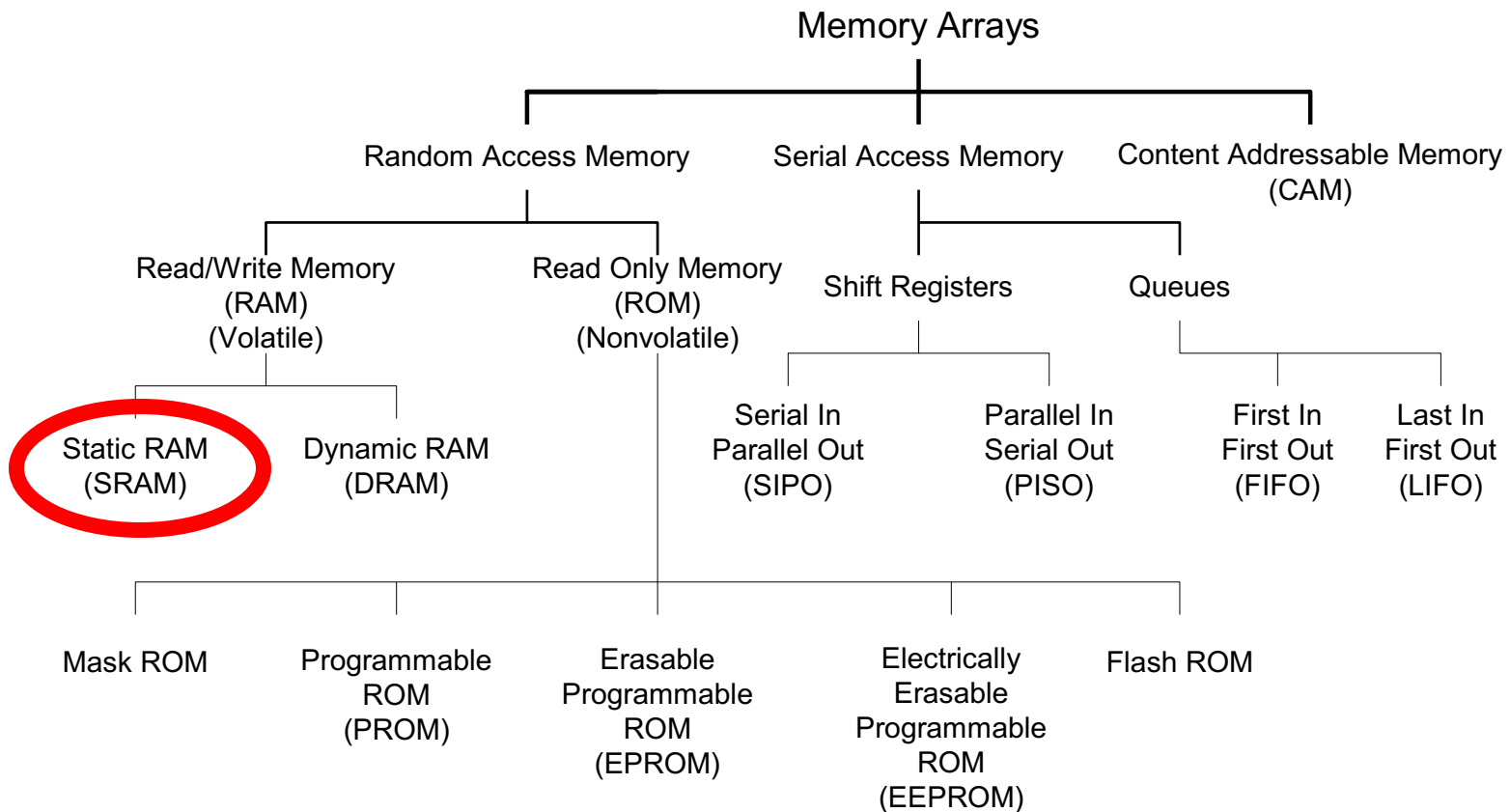
Memory Arrays



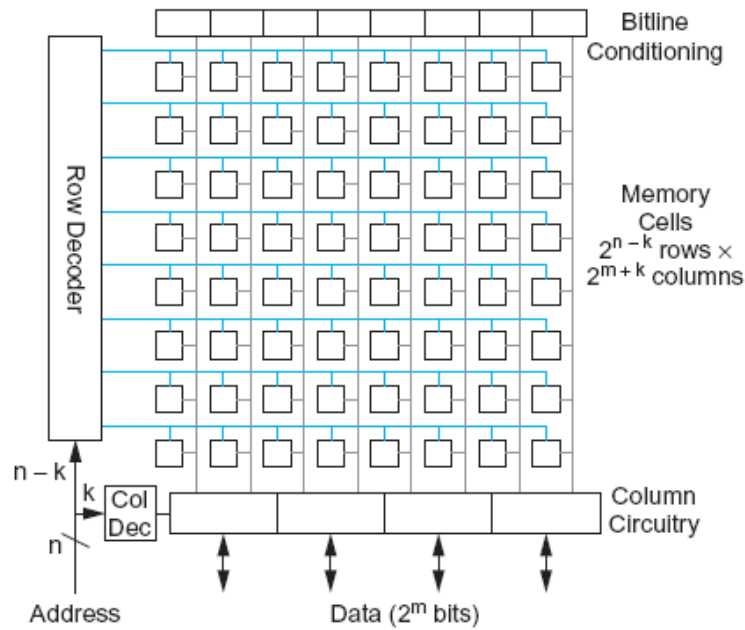
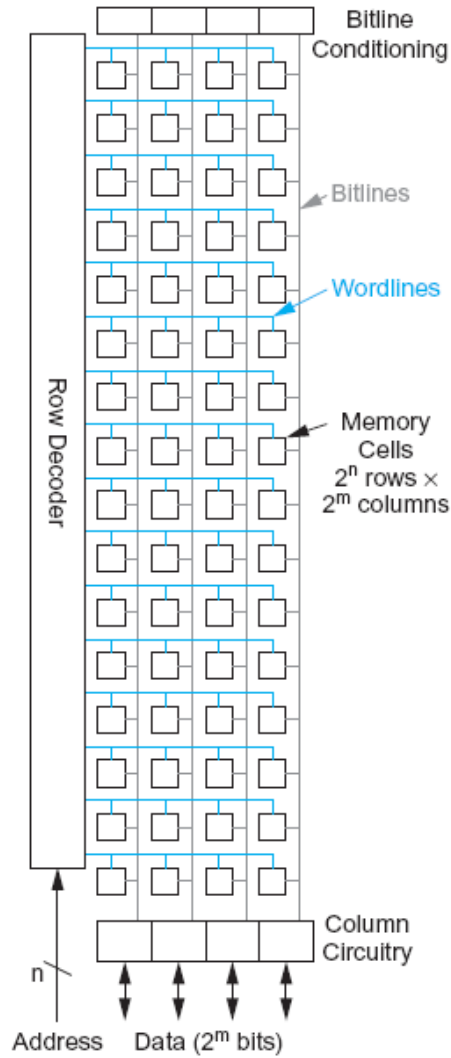
Memory Arrays



Memory Arrays



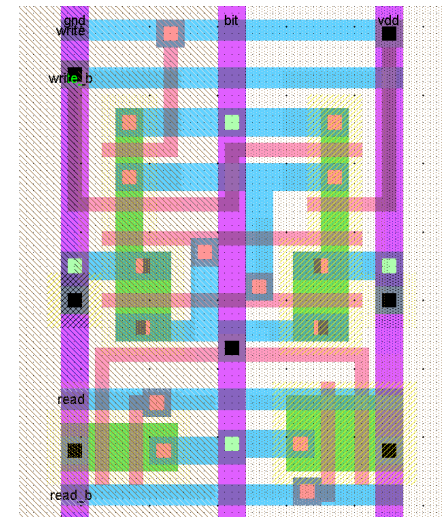
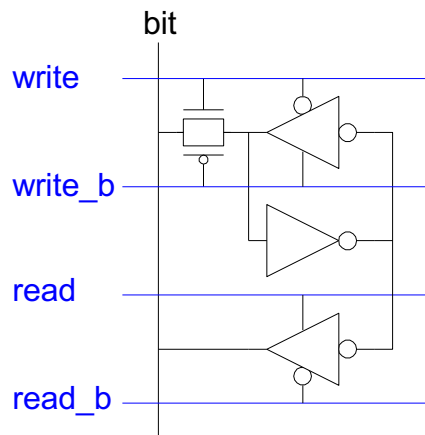
Array Architecture



- ❑ 2^n words of 2^m bits each
- ❑ If $n \gg m$, bit lines too long/slow
 - fold by 2^k into fewer rows of more columns
- ❑ Good regularity – easy to design
- ❑ Very high density if good cells are used

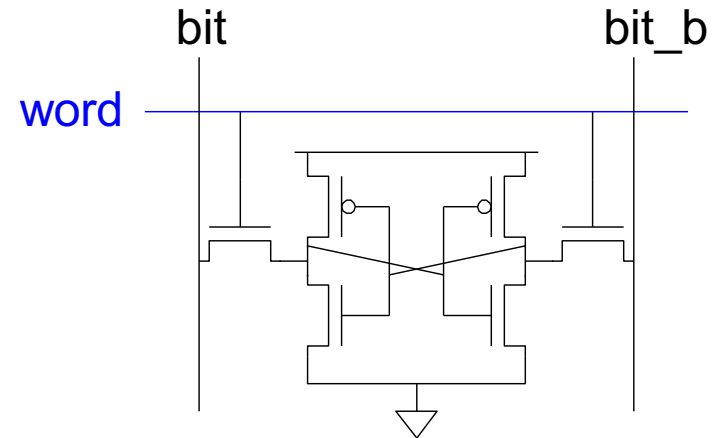
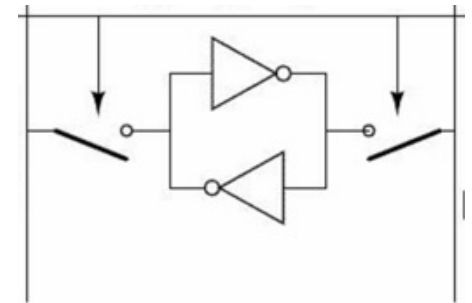
Brute Force: 12T SRAM Cell

- ❑ Basic building block: SRAM Cell
 - Holds one bit of information, like a latch
 - Must be read and written
- ❑ *Brute force approach*: 12-transistor (12T) SRAM cell
 - Use a simple latch connected to bitline
 - 46 x 75 λ unit cell – **very large**



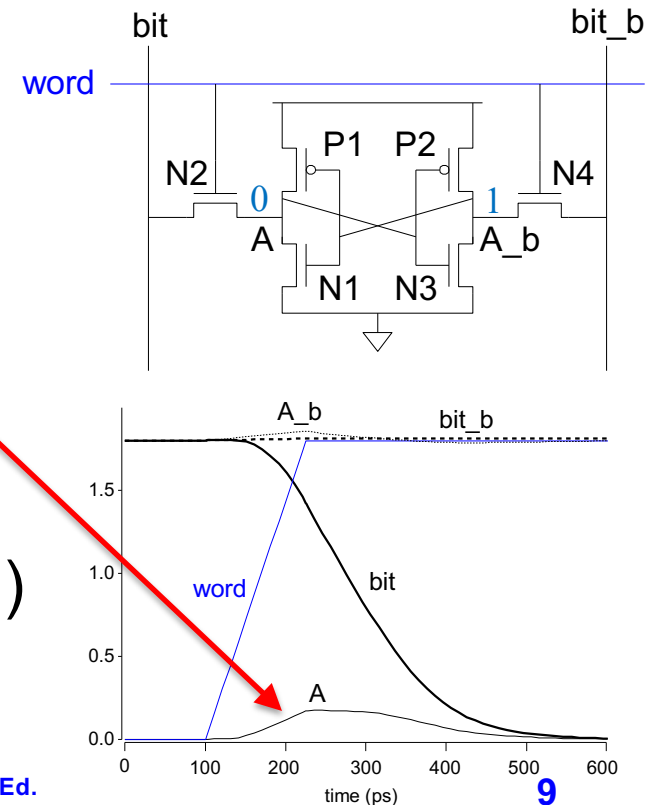
6T SRAM Cell

- ❑ Cell size accounts for most of array size
 - Reduce cell size at expense of complexity
- ❑ 6T SRAM Cell
 - Used in most commercial chips
 - Data stored in cross-coupled inverters
- ❑ Read:
 - Precharge bit, bit_b
 - Raise wordline
- ❑ Write:
 - Drive data onto bit, bit_b
 - Raise wordline



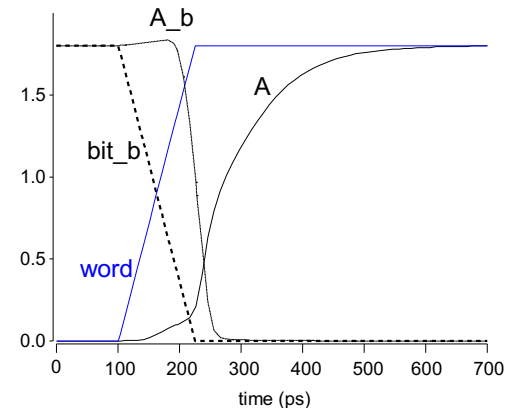
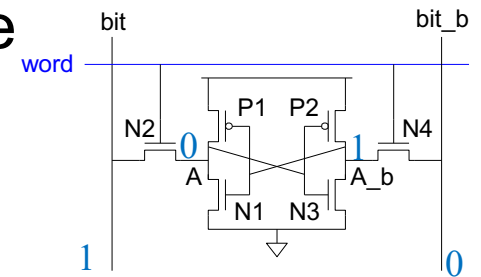
SRAM Read

- ❑ Precharge both bitlines high
- ❑ Then turn on wordline
- ❑ One of the two bitlines will be pulled down by the cell
- ❑ Ex: $A = 0, A_b = 1$
 - bit discharges, bit_b stays high
 - But A bumps up slightly
- ❑ *Read stability*
 - A must not flip
 - $N1 \gg N2$ (& $N3 \gg N4$)
 - N2-current source (saturation)
 - N1-resistor (triode)



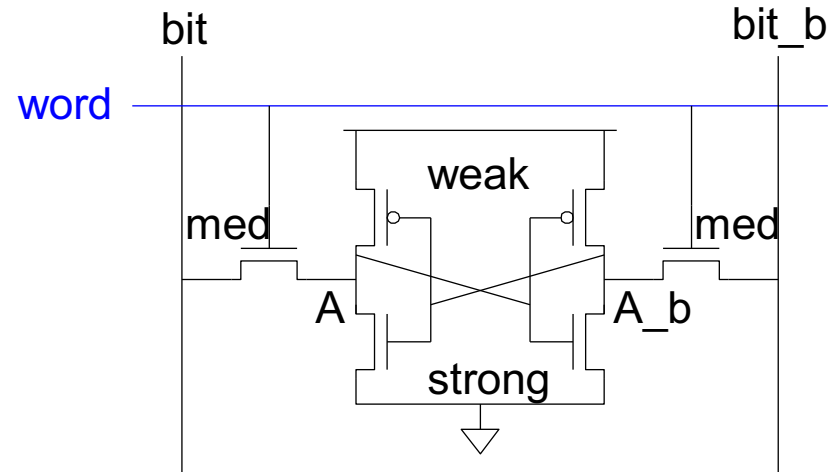
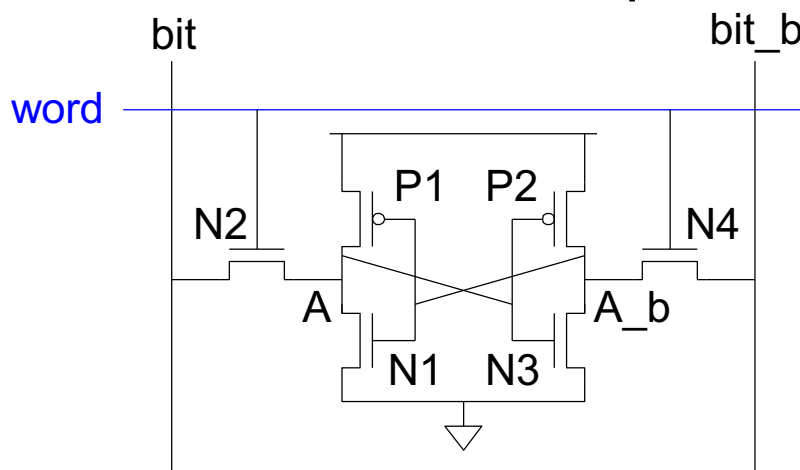
SRAM Write

- ❑ Drive one bitline high, the other low
- ❑ Then turn on wordline
- ❑ Bitlines overpower cell with new value
- ❑ Ex: $A = 0$, $A_b = 1$, $\text{bit} = 1$, $\text{bit_b} = 0$
 - Force A_b low, then A rises high
- ❑ *Writability*
 - Must overpower feedback inverter
 - $N4 \gg P2$ (& $N2 \gg P1$)
 - $N4$ initially a current source
 - $P2$ initially a resistor
 - As A_b drops to V_{tn} these roles swap



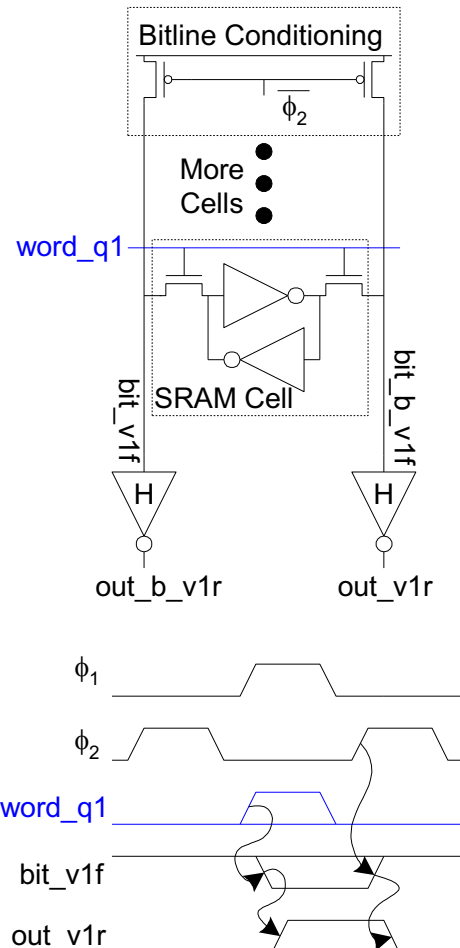
SRAM Sizing

- ❑ Three unknowns ($N1$, $N2$, $P1$) and three constraints:
 1. **Read stability**: High bitlines must not overpower inverters during reads: $N1$ “stronger” than $N2$
 2. **Writability**: But low bitlines must write new value into cell: $N2$ “stronger” than $P1$
 3. **Read speed**: dictated by size of $N2$ *within a range*
- ❑ Write out three equations and solve for $N1$, $N2$, $P1$

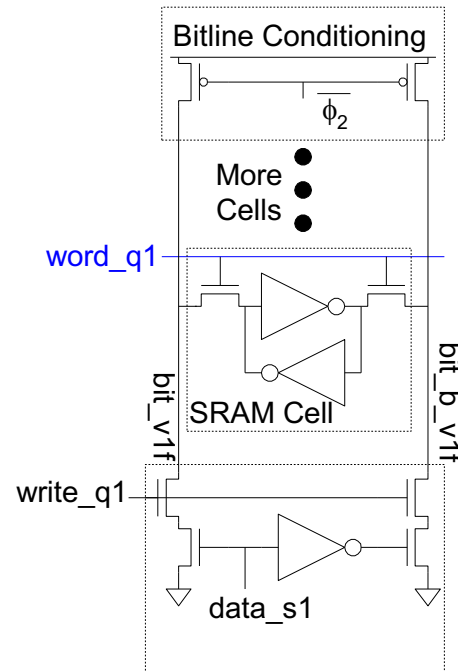


SRAM Column Example

Read



Write

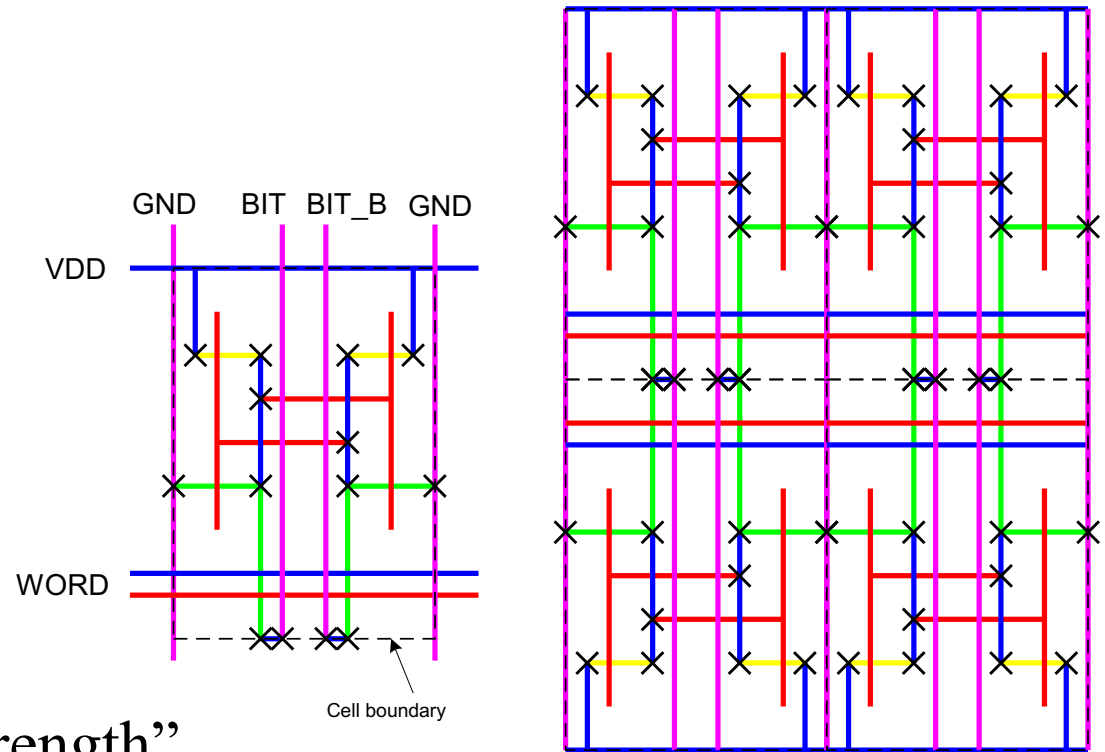
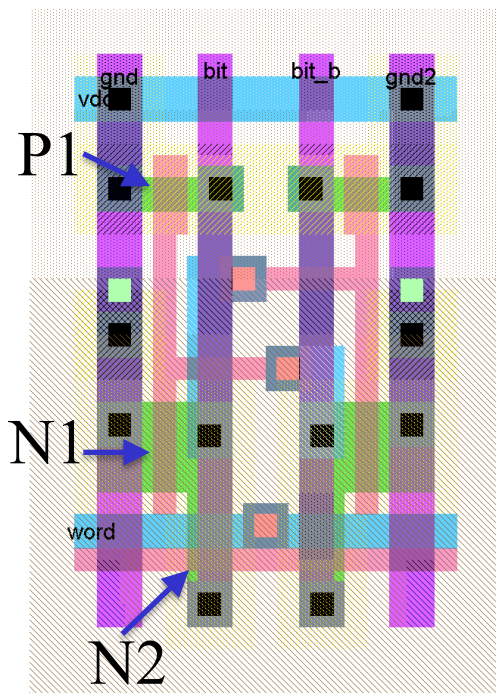


- ❑ Large-signal read
 - For small arrays

- ❑ Need a differential “sense” amplifier
 - To speed up for large arrays
 - To add tolerance to CM noise

SRAM Layout

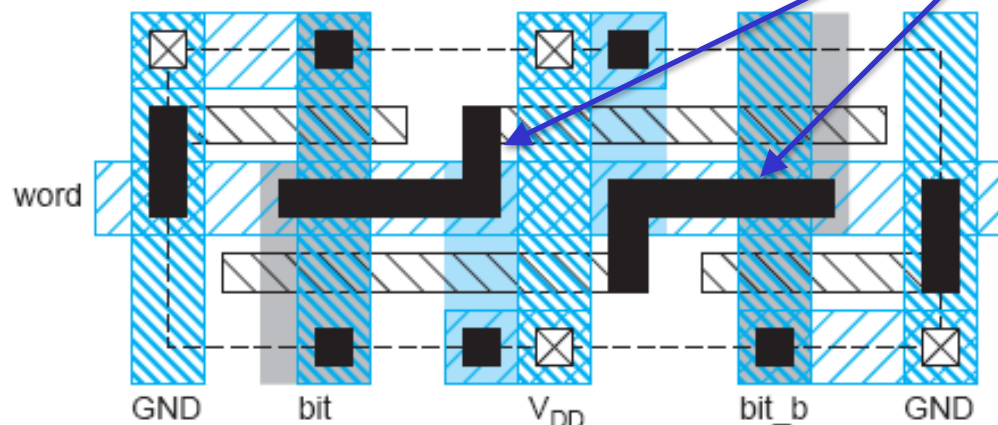
- ❑ Cell size is critical: $26 \times 45 \lambda$ (even smaller in industry)
- ❑ Tile cells sharing V_{DD} , GND, bitline contacts



$N1 \gg N2 \gg P1$ wrt “strength”

6T Thin Cell

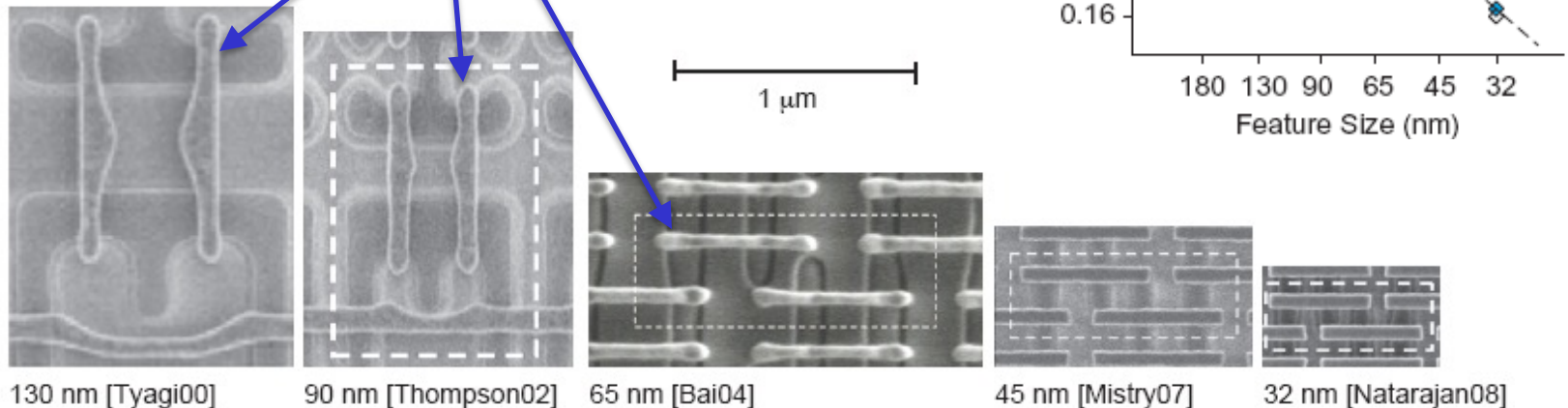
- ❑ In nanometer CMOS
 - Avoid bends in polysilicon and diffusion
 - Orient all transistors in one direction
- ❑ *Lithographically friendly* or *thin-cell* layout does this
 - Diffusion – only vertical; Poly – only horizontal
 - Uses local interconnect with trench contacts
 - Also reduces length and capacitance of bitlines



Commercial SRAMs

- ❑ Five generations of Intel SRAM cell micrographs
 - Transition to thin cell at 65 nm
 - Steady scaling of cell area

No bends in polysilicon

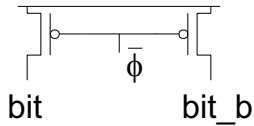


Column Circuitry

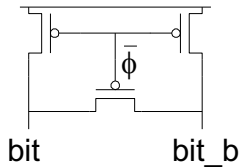
- ❑ Some circuitry is required for each column
 - Bitline conditioning
 - Sense amplifiers
 - Column multiplexing

Bitline Conditioning

- ❑ Precharge bitlines high before reads



- ❑ Equalize bitlines to minimize voltage difference when using sense amplifiers

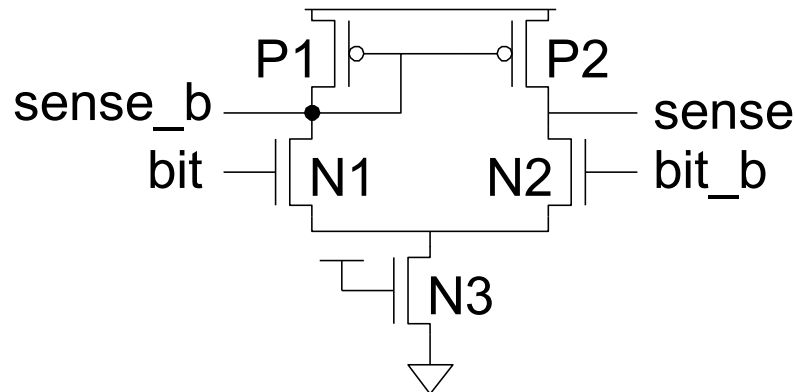


Sense Amplifiers

- ❑ Bitlines have many cells attached
 - Ex: 32-kbit SRAM has 128 rows x 256 cols
 - 128 cells on each bitline
- ❑ $t_{pd} \propto (C/I) \Delta V$
 - Even with shared diffusion contacts, 64C of diffusion capacitance (large C)
 - Discharged slowly through small transistors (small I)
- ❑ *Sense amplifiers* are triggered on small voltage swing (reduce ΔV)

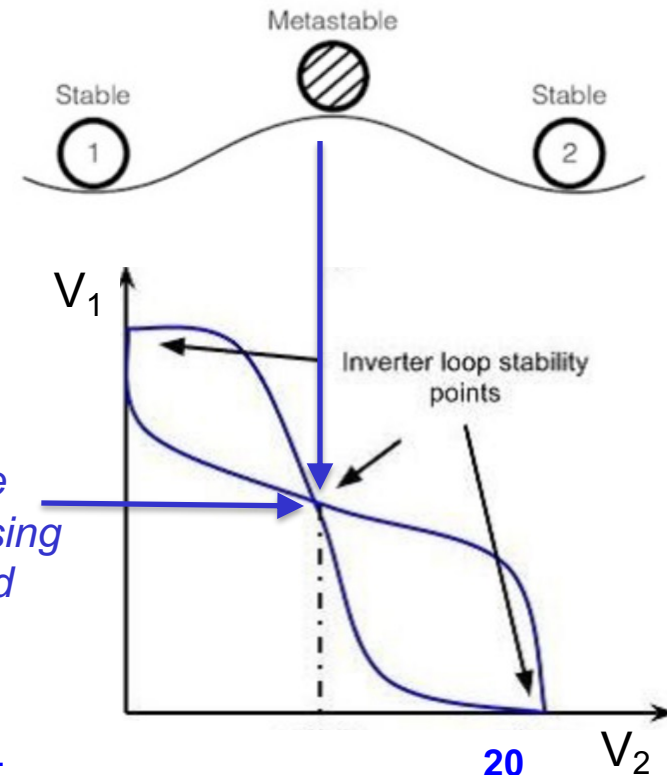
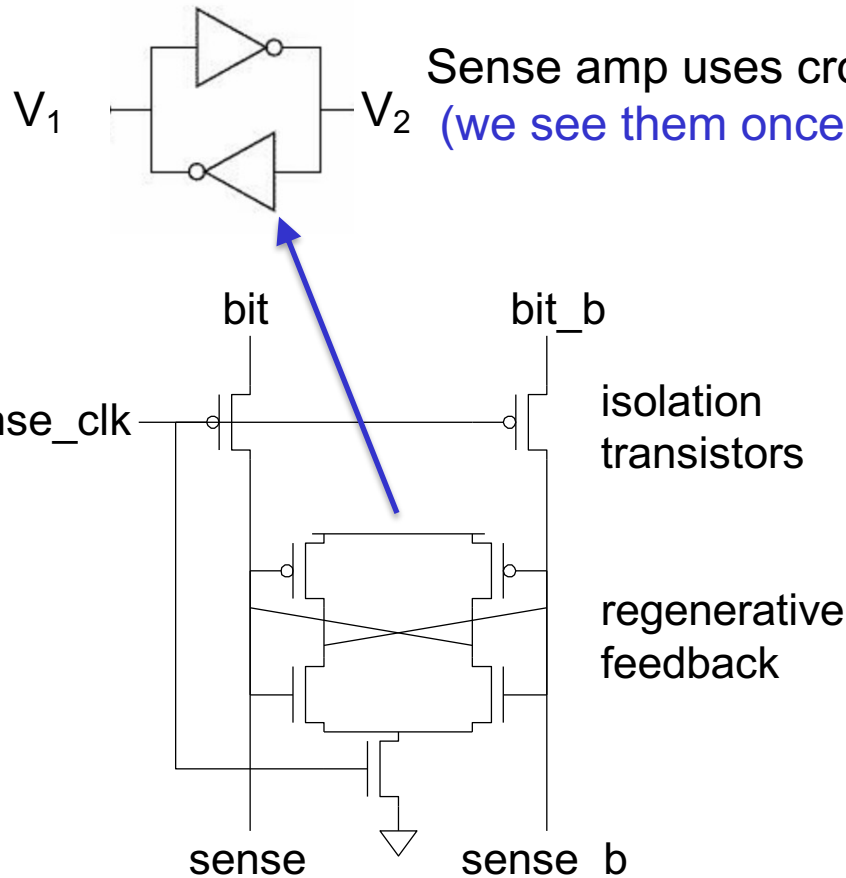
Brute Force: Differential Pair Amp

- ❑ Differential pair **requires no clock**
- ❑ But **always dissipates static power** – not a good choice



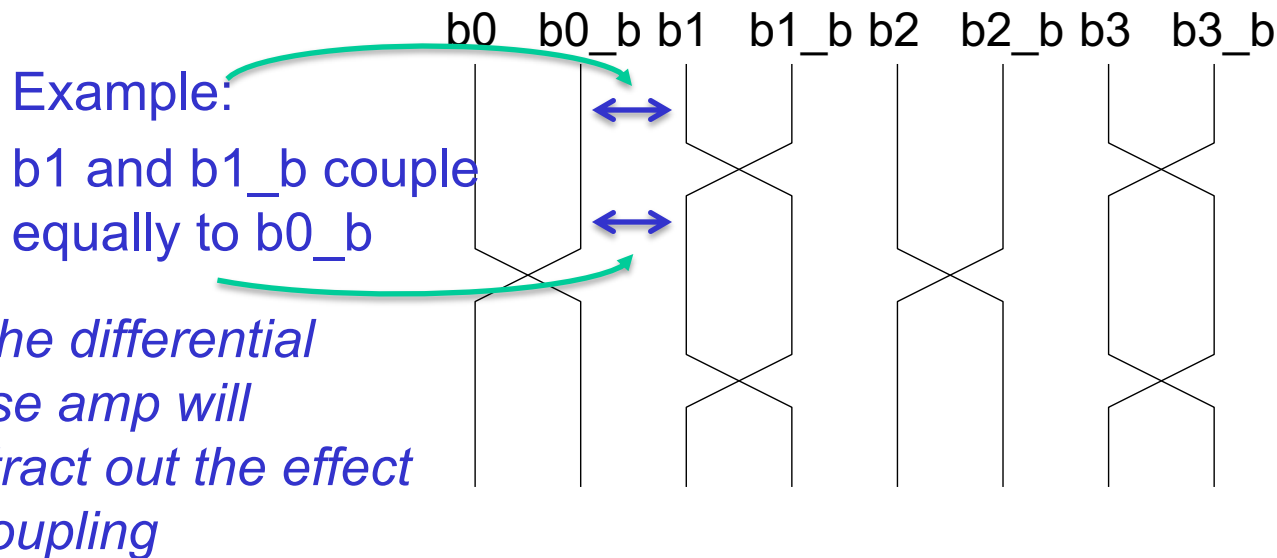
Clocked Sense Amp

- ❑ Clocked sense amp **saves power**
- ❑ Requires sense_clk after enough bitline swing
- ❑ Isolation transistors cut off large bitline capacitance



Twisted Bitlines

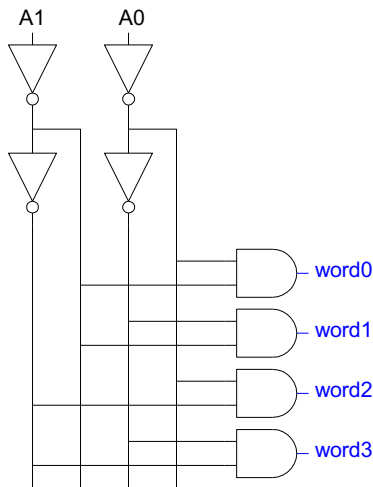
- ❑ Sense amplifiers also amplify noise
 - Coupling noise is severe in modern processes
 - Try to couple equally onto bit and bit_b
 - Done by *twisting* bitlines



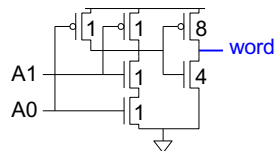
Decoders

- ❑ $n:2^n$ decoder consists of 2^n n -input AND gates
 - One needed for each row of memory
 - Build AND from NAND or NOR gates

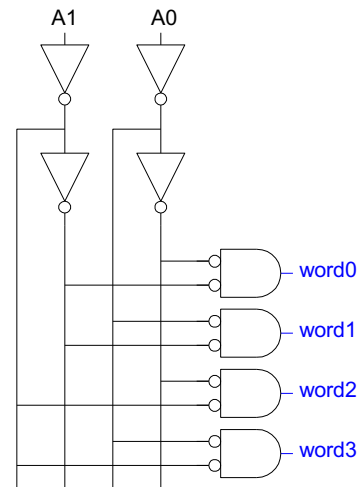
Static CMOS



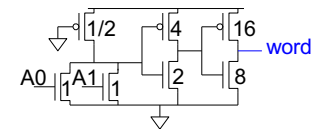
NAND + INV



Pseudo-nMOS (power too high)

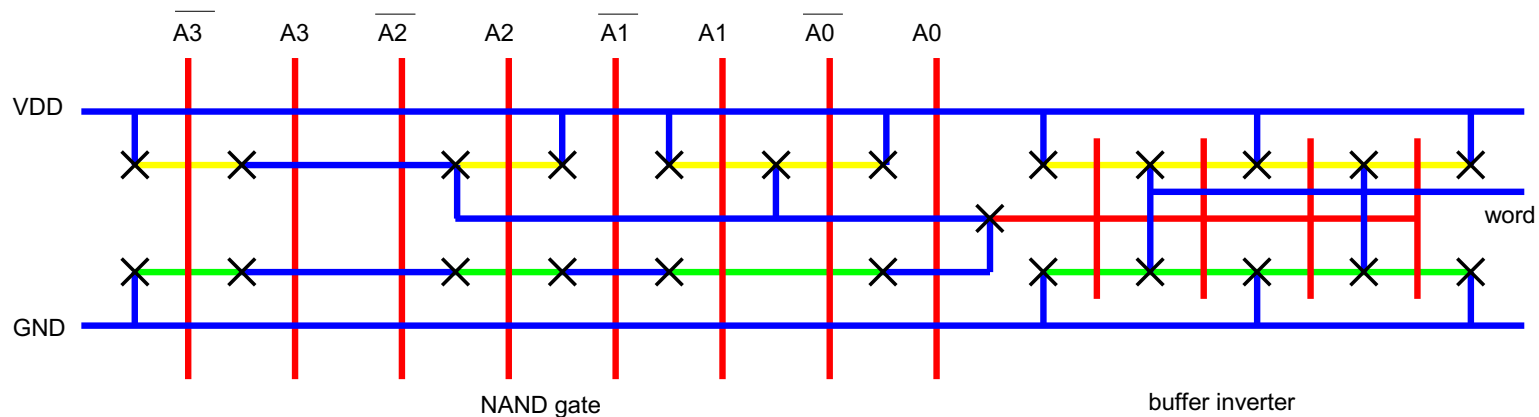


NOR + INV + INV



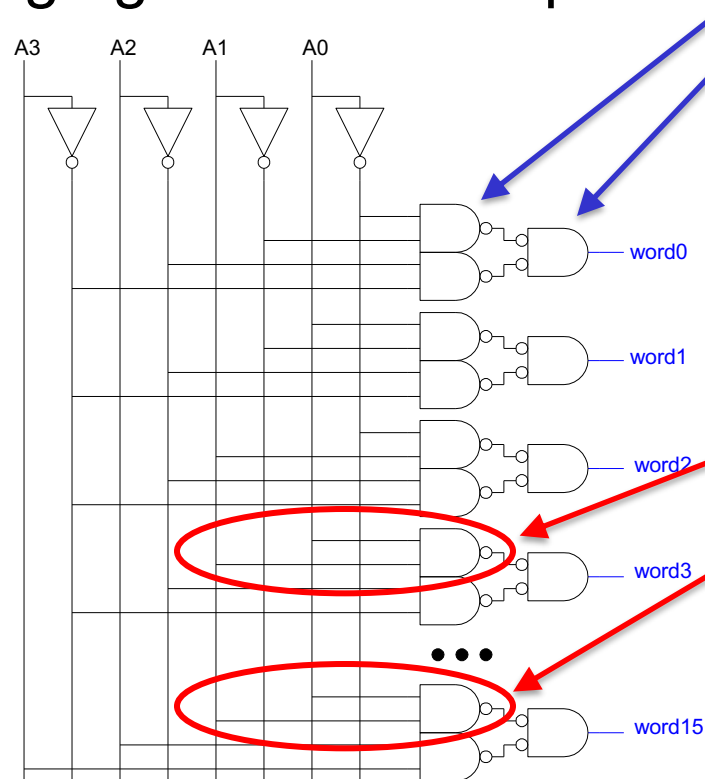
Decoder Layout

- ❑ Decoders must be pitch-matched to SRAM cell
 - Requires very skinny gates



Large Decoders

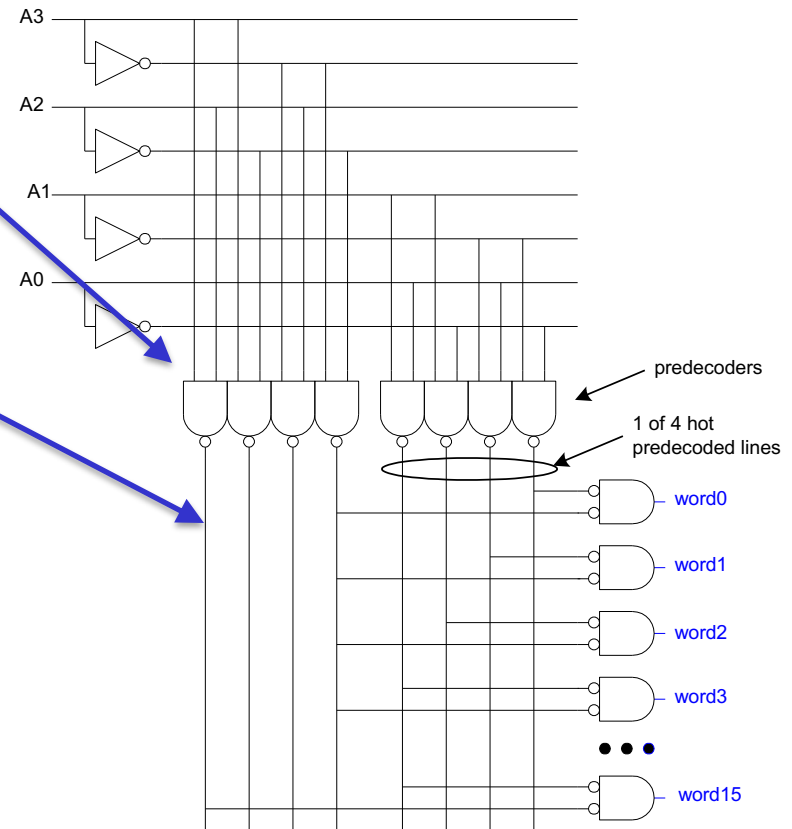
- ❑ For $n > 4$, NAND gates become slow
 - Break large gates into multiple **smaller gates**



Redundant computations
→ wasted area / power

Predecoding

- Many of these gates are **redundant** (see previous slide)
 - Factor out common gates into predecoder
 - And “broadcast” partial results vertically (instead of address bits)
 - Saves area**
 - Same path effort
-
- The diagram illustrates a 4-to-1 multiplexer implementation. At the top, four address inputs are labeled A3, A2, A1, and A0. Each input line has a buffer and an inverter, creating both true and complemented signals. These signals are connected to a grid of gates. The first four columns of gates are 4-input AND gates, each receiving one true and one complemented address signal. These are labeled 'predecoders' and '1 of 4 hot predecoded line'. The outputs of these predecoders are connected to the inputs of four 2-input AND gates, which are labeled 'word0', 'word1', 'word2', and 'word3'. A blue arrow points from the text 'broadcast partial results vertically' to the vertical lines connecting the predecoder outputs to the word-level AND gates. Another blue arrow points from the text 'instead of address bits' to the inputs of the word-level AND gates.

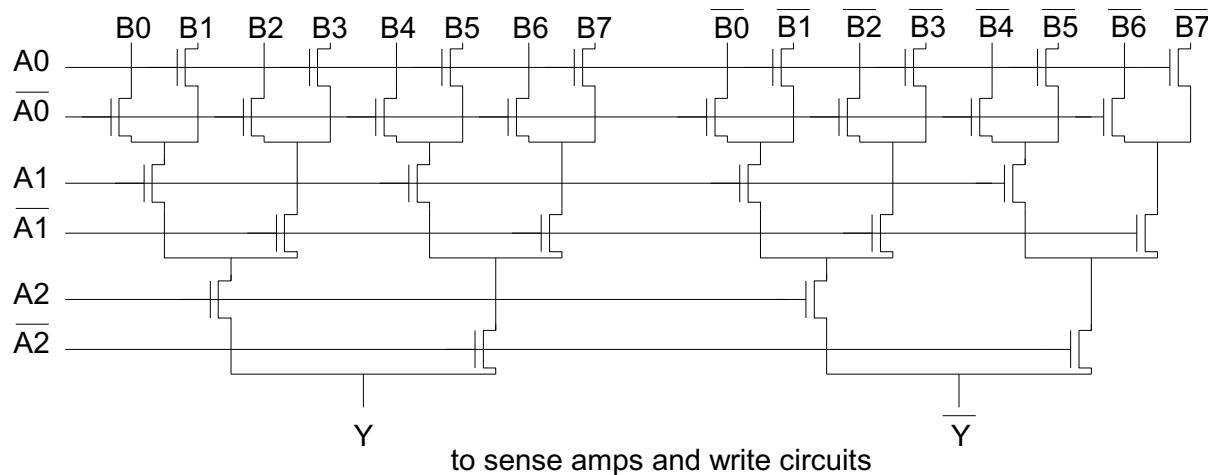


Column Multiplexing

- ❑ Recall that array may be folded for good aspect ratio
- ❑ Ex: 2 kword x 16 folded into 256 rows x 128 columns
 - Must select 16 output bits from the 128 columns
 - Requires 16 8:1 column multiplexers

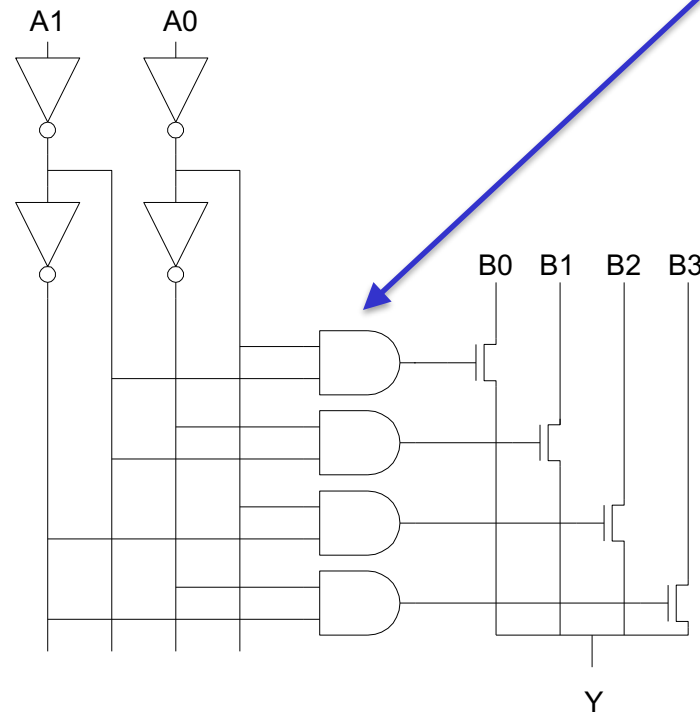
Tree Decoder Mux

- ❑ Column mux can use pass transistors
 - Use nMOS only, precharge outputs
- ❑ One design is to use k series transistors for $2^k:1$ mux
 - No external decoder logic needed, but is **slow (RC ladder)**



Single Pass-Gate Mux

- ❑ Eliminate series transistors by separate decoder to speed up

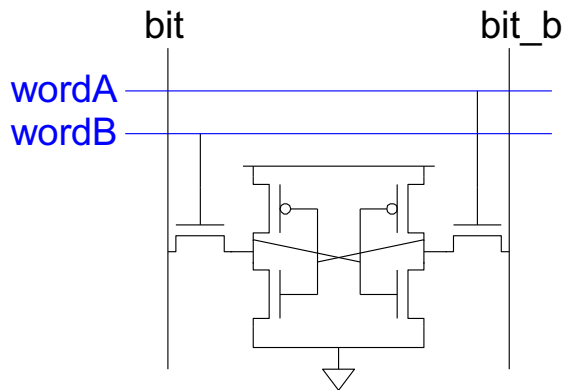


Multiple Ports

- ❑ We have considered single-ported SRAM
 - One read or one write on each cycle
- ❑ *Multiported SRAM are needed for register files*
- ❑ Examples:
 - Pipelined MIPS must read two sources and write a third result each cycle
 - Multicycle MIPS must read two sources or write a result on some cycles
 - Superscalar MIPS must read and write many sources and results each cycle

Dual-Ported SRAM

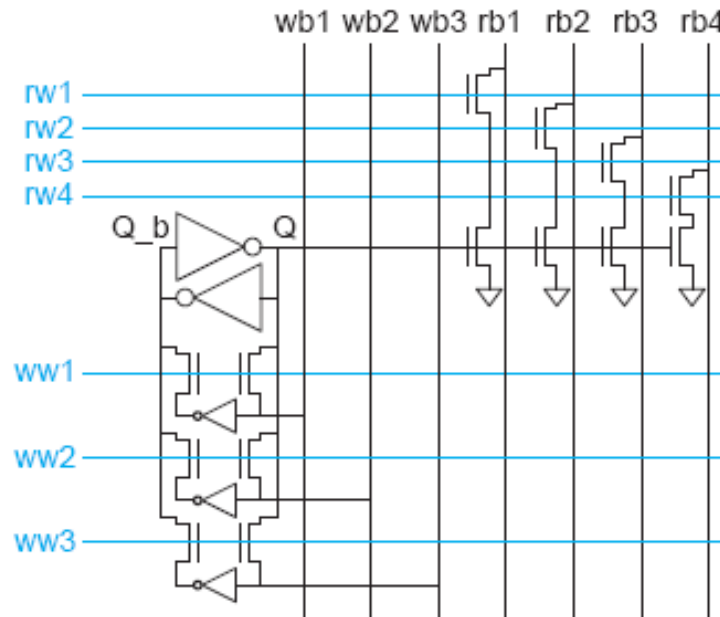
- ❑ Simple dual-ported SRAM
 - Two independent single-ended reads
 - Or one differential write



- ❑ Do two reads and one write by time multiplexing
 - Read during ph1, write during ph2

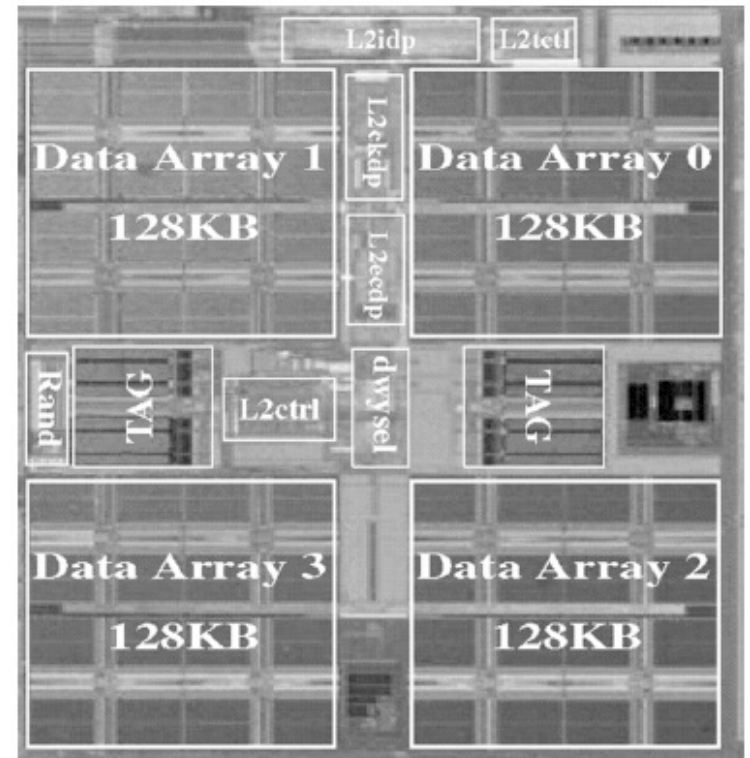
Multi-Ported SRAM

- ❑ Adding more access transistors **hurts read stability**
- ❑ Multiported SRAM isolates reads from state node
- ❑ Single-ended bitlines save area



Large SRAMs

- ❑ Large SRAMs are split into subarrays for speed
- ❑ Ex: UltraSparc 512KB cache
 - 4 128 KB subarrays
 - Each have 16 8KB banks
 - 256 rows x 256 cols / bank
 - 60% subarray area efficiency
 - Also space for tags & control



[Shin05]